

Description

The IRFR3709ZTRPBF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

D

TO252-2L

General Features

 $V_{DS} = 30V I_{D} = 80 A$

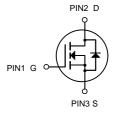
 $R_{DS(ON)} < 6.8 m\Omega$ @ $V_{GS} = 10 V$

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
IRFR3709ZTRPBF	TO252-2L	RFR3709 XXXX	2500

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage	±20	V
	Drain Current – Continuous (T _C =25°C)	80	А
I _D	Drain Current – Continuous (T _C =100°C)	51	А
Ірм	Drain Current – Pulsed¹	320	А
EAS	Single Pulse Avalanche Energy ²	88	mJ
IAS	Single Pulse Avalanche Current ²	42	А
_	Power Dissipation (T _C =25°C)	54	W
P _D	Power Dissipation – Derate above 25°C	0.43	W/°C
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R ₀ JA	Thermal Resistance Junction to ambient	62	°C/W
Rejc	Thermal Resistance Junction to Case	2.3	°C/W



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
△BVDSS/△TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.04		V/°C
IDOO	Desir Course Leaders Course	V _{DS} =30V , V _{GS} =0V , T _J =25°C			1	uA
IDSS	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =125°C	-		10	uA
IGSS	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	-		±100	nA
DDC(ON)	Static Drain-Source On-Resistance ³	V _{GS} =10V , I _D =20A		5	6.8	mΩ
RDS(ON)		V _{GS} =4.5V , I _D =10A	-	6.5	9	mΩ
VGS(th)	Gate Threshold Voltage	V V I 050.4	1	1.6	2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, I_{D} =250uA		-4		mV/°C
gfs	Forward Transconductance	V _{DS} =10V , I _D =10A		18		S
Q_g	Total Gate Charge ^{3, 4}			11.1		
Qgs	Gate-Source Charge ^{3, 4}	V _{DS} =15V , V _{GS} =4.5V , I _D =20A	I	1.85		nC
Qgd	Gate-Drain Charge ^{3,4}			6.8	1	
Td(on)	Turn-On Delay Time ^{3,4}		I	7.5		
T _r	Rise Time ^{3, 4}	V_{DD} =15V , V_{GS} =10V , R_G =3.3 Ω	I	14.5	1	ns
Td(off)	Turn-Off Delay Time ^{3,4}	I _D =15A	I	35.2	1	
T _f	Fall Time ^{3,4}			9.6		
Ciss	Input Capacitance	V _{DS} =25V , V _{GS} =0V , F=1MHz	I	1160	1	pF
Coss	Output Capacitance		-	200		
Crss	Reverse Transfer Capacitance			180		
R_g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	2.5	-	Ω
EAS	Single Pulse Avalanche Energy	V _{DD} =25V, L=0.1mH, IAS=20A	20			mJ
IS	Continuous Source Current	V _G =V _D =0V , Force Current			80	Α
ISM	Pulsed Source Current ³				320	Α
VSD	Diode Forward Voltage ³	V _{GS} =0V , I _S =1A , T _J =25°C			1	٧
trr	Reverse Recovery Time	VGS=0V,IS=1A , di/dt=100A/μs T _J =25°C				ns
Q _{rr}	Reverse Recovery Charge					nC

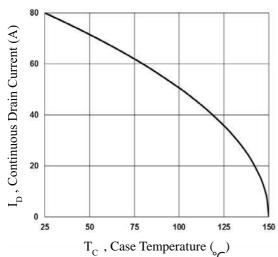


Fig.1 Continuous Drain Current vs. Tc

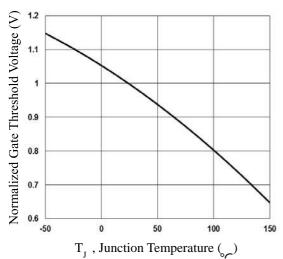


Fig. 3 Normalized Vth vs. Tj

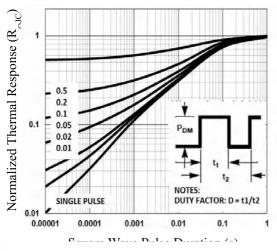


Fig.5 Normalized Transient Impedance

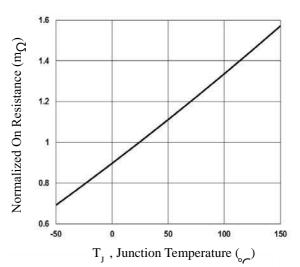


Fig.2 Normalized RDSON vs. Tj

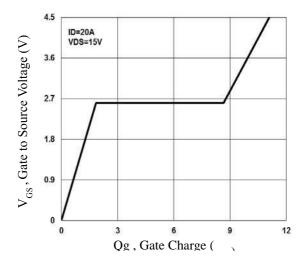


Fig. 4 Gate Charge Waveform

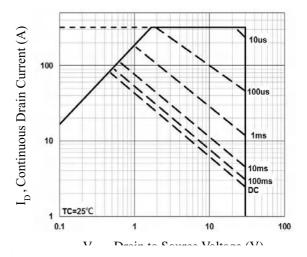
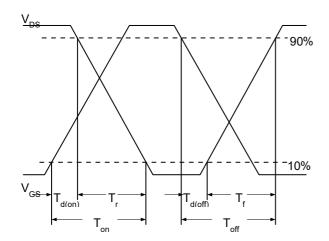


Fig.6 Maximum Safe Operation Area

IRFR3709ZTRPBF

N-Channel Enhancement Mode MOSFET



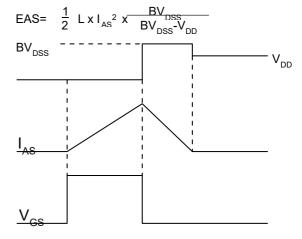
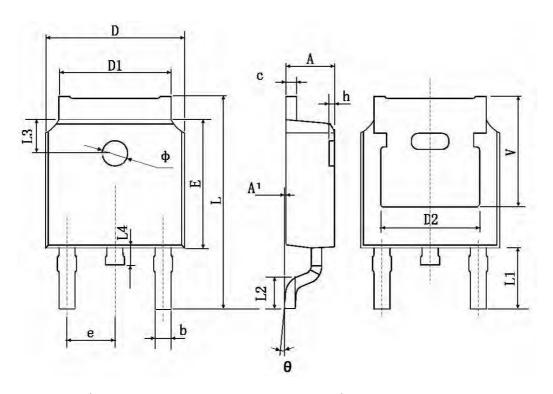


Fig. 7 Switching Time Waveform

Fig. 8 EAS Waveform

TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		

Attention

- Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.
- HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.
- Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production.

 HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.